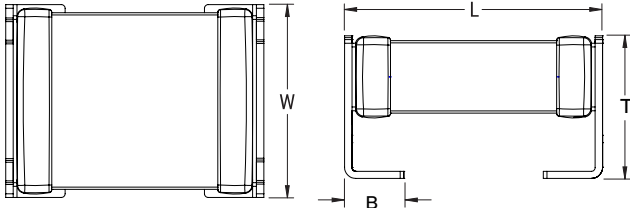


TOP VIEW  
Single or Double Chip Stack

PROFILE VIEW  
Single Chip Stack



Click [here](#) for the 3D model.

**General Information**

Series	KPS SMD Comm X8L HT150C
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Single Chip, High Temperature
Features	High Temperature
RoHS	Yes
Termination	Tin
Typical Component Weight	410 mg
Shelf Life	78 Weeks
MSL	1

**Dimensions**

L	6mm +/-0.5mm
W	5mm +/-0.5mm
T	3.5mm +/-0.30mm
B	1.6mm +/-0.3mm

**Packaging Specifications**

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	1300

**Specifications**

Capacitance	3.3 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8L
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+15% (-55C to +125C), +15/-40% (125C to 150C), 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	151.5 MOhms

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